



FIG. 1A

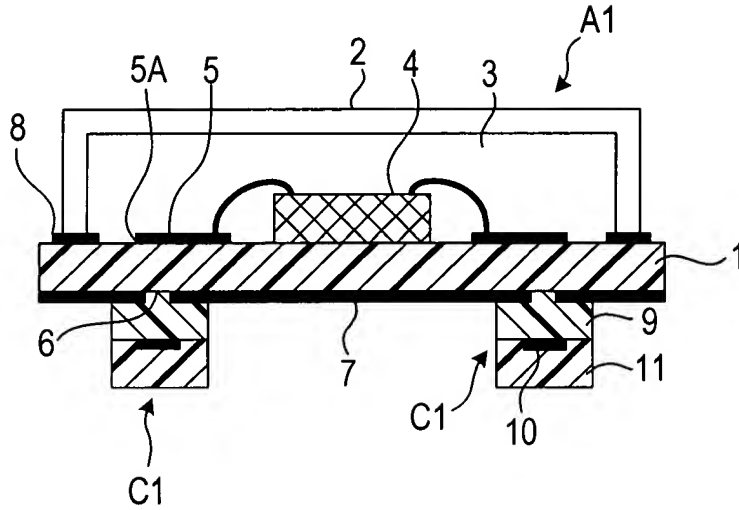


FIG. 1B

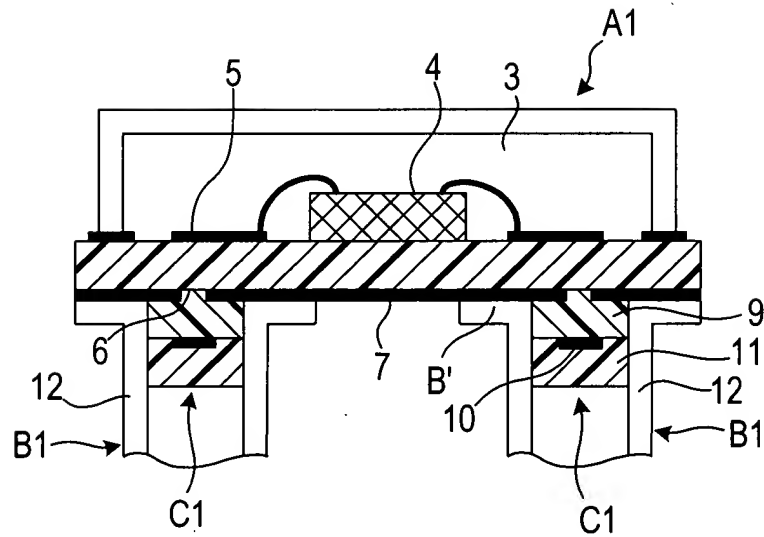




FIG. 2A

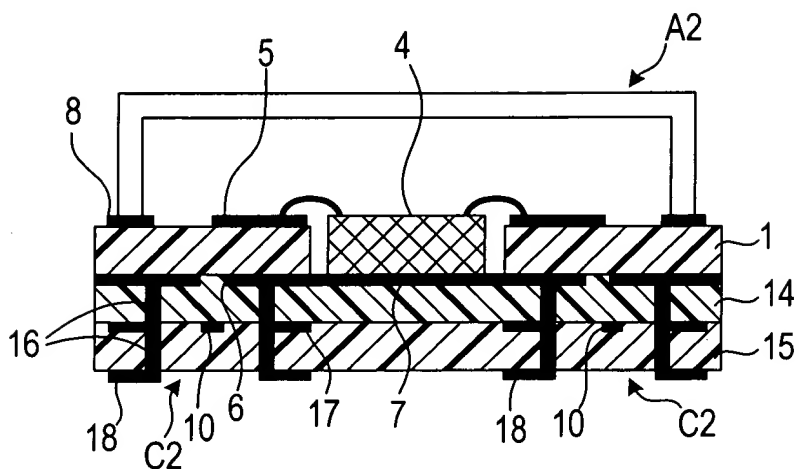


FIG. 2B

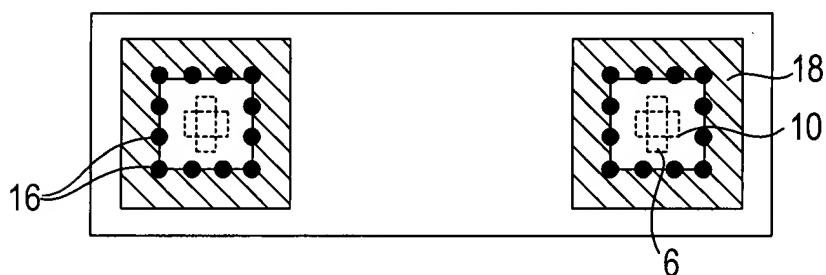


FIG. 2C

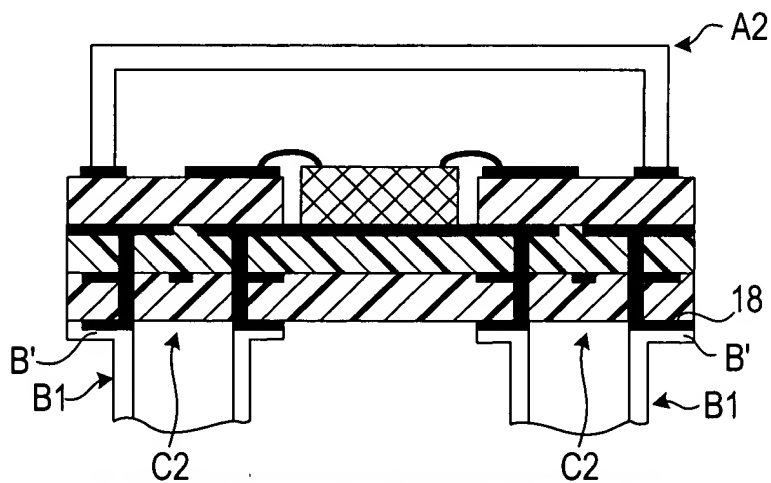


FIG. 2D

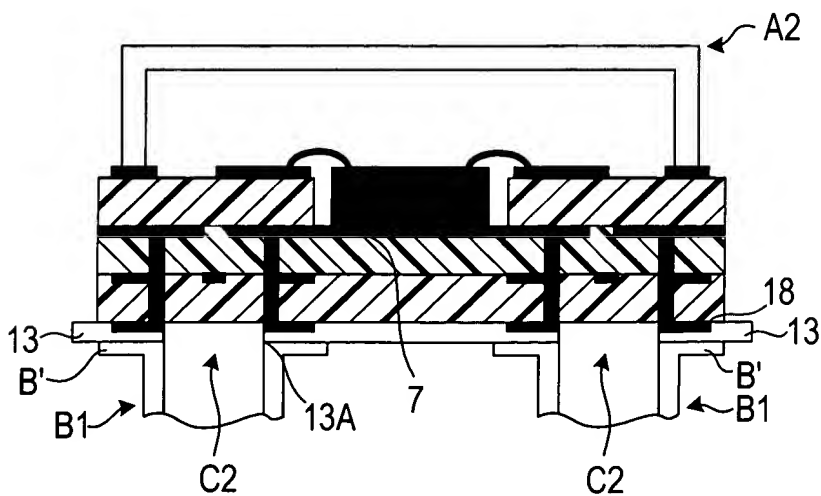


Fig. 1 is a cross-sectional view of a semiconductor device. It shows a substrate 1 with a top layer 8 and a bottom layer 5. A central region 6 is defined by a vertical wall. A horizontal layer 20 is located within this central region. Dimensions L2 and L3 are indicated. A dashed line X-X' is shown at the bottom.

Figure 1 is a cross-sectional view of a semiconductor device. It shows a substrate 1 with a top layer 8 and a bottom layer 5. A central region 6 is defined by a dashed line. Two horizontal layers 20 are positioned above and below the central region 6. Dimensions L2 and L3 are indicated, along with a coordinate X.

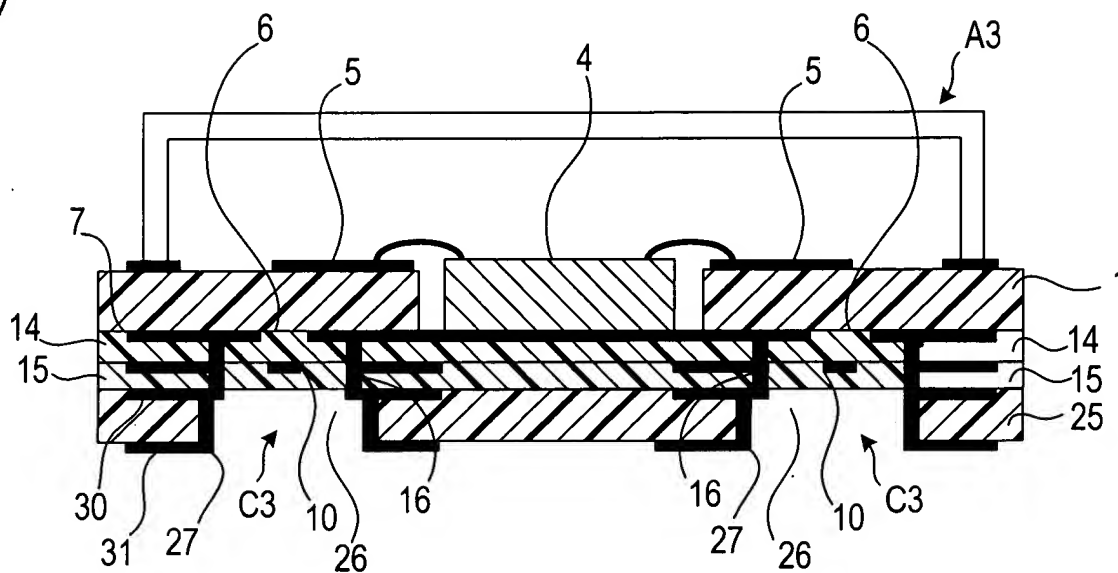


FIG. 5

Figure 1 is a schematic diagram of a semiconductor device 10. The device consists of a rectangular substrate. Within this substrate, there are two square regions, B1 and C2, each containing a 3x3 grid of dots. The regions B1 and C2 are separated by a horizontal gap. Dimensions are indicated: P1 is the vertical distance from the top edge of the substrate to the top edge of region B1; Q1 is the vertical distance from the top edge of region B1 to the top edge of region C2; P2 is the vertical distance from the bottom edge of the substrate to the bottom edge of region B1; and Q2 is the vertical distance from the bottom edge of region B1 to the bottom edge of region C2. A label 16 points to the grid of dots in region C2.

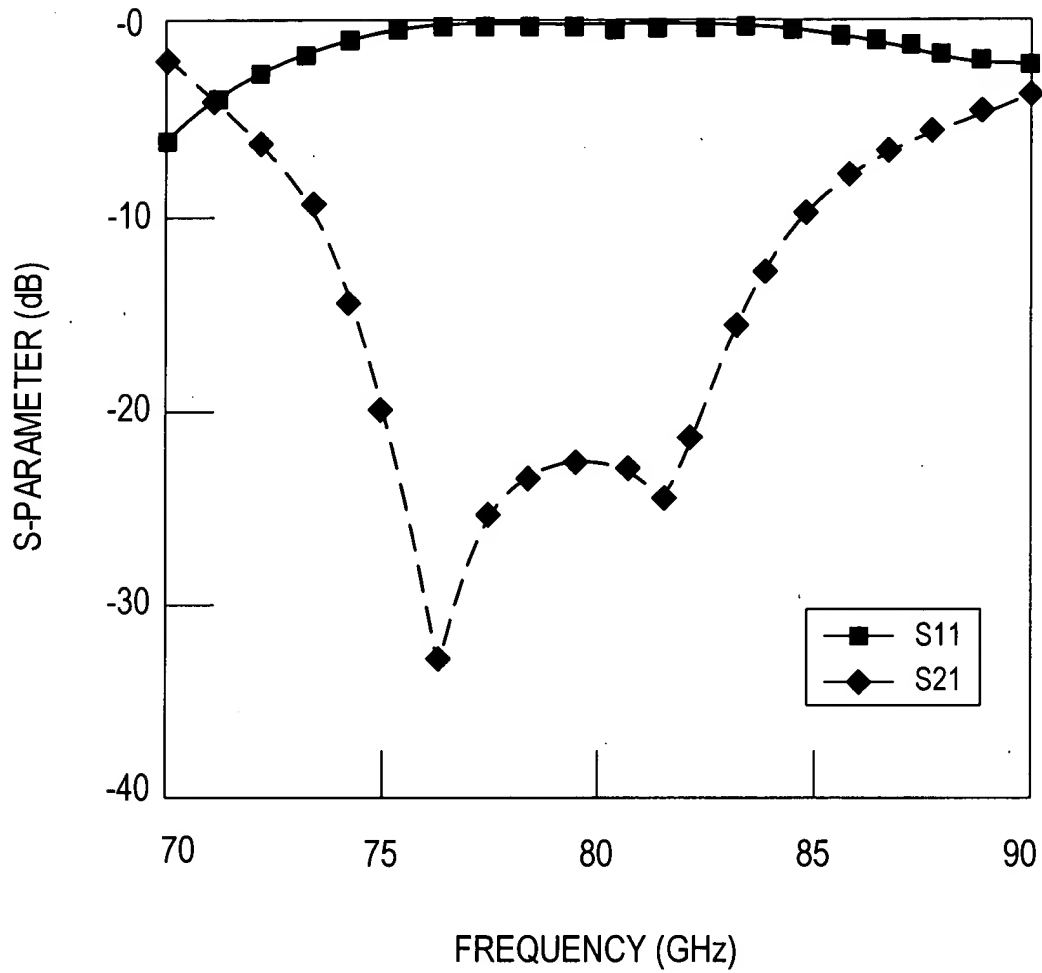
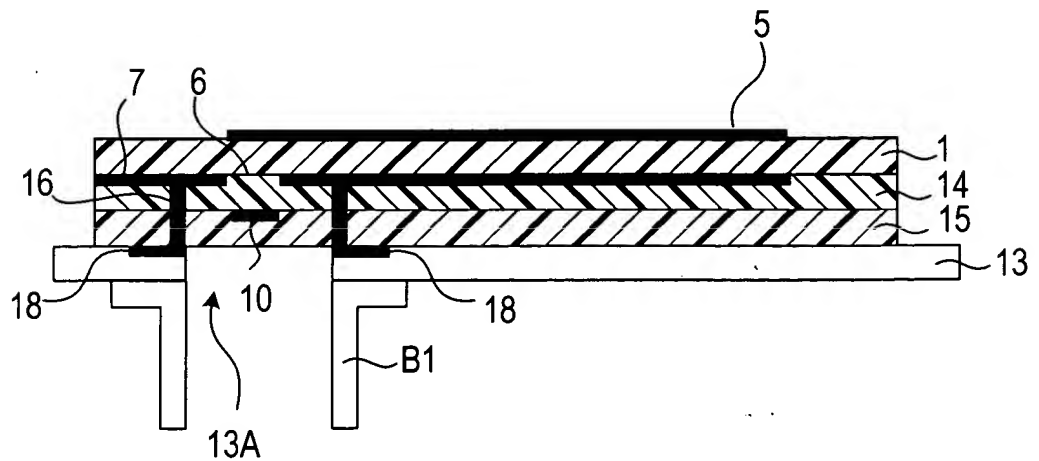


FIG. 7

FIG. 8



[illegible]

A cross-sectional view of a semiconductor device 100. The device features a substrate 1 with a central region 4 containing a cross-hatched pattern. This central region is flanked by two regions 5, each containing a circular feature 6. Above the central region 4, there is a layer 8. Below the central region 4, there is a layer 16. The device is further defined by regions 10, 17, 18, and 15. A label C2 points to the bottom of the device, and a label A2 points to the top of the device.

Figure 1 is a schematic diagram of a rectangular device 6. The device consists of a central square region 10, which contains a dashed cross pattern. This central region is surrounded by a ring of 16 dots 16. The entire assembly is enclosed within a rectangular frame 18.

A cross-sectional view of a semiconductor device. A central bridge structure, labeled 18, is positioned over a substrate. The bridge structure consists of a central layer with a cross-hatched pattern, flanked by two layers with diagonal hatching. Below the bridge, the substrate has two main regions, B' and B1, separated by a central gap. Arrows labeled C2 point upwards from the substrate towards the bridge. A top layer, labeled A2, is shown above the bridge structure, with a wavy arrow pointing to it from the top right. The bottom right corner of the diagram is labeled A2.

Fig. 1 is a schematic cross-sectional view of a semiconductor device. It shows a substrate 1 with a top layer 8 and a bottom layer 5. A central region 6 is defined by a dashed line. Four square regions 20 are located within this central region. Arrows indicate dimensions L2 and L3, and a coordinate system with X1 and X2 axes is shown.

A cross-sectional view of a device. It shows a substrate 6 with a hatched pattern. On top of the substrate, there are several layers. Layer 8 is the topmost layer, followed by layer 20, then layer 5. Layer 7 is a thin layer on the right side of the substrate. Layer 6 is the substrate itself.

A detailed cross-sectional diagram of a semiconductor device. The structure consists of several stacked layers: a top layer labeled 1, followed by layers 14 and 15. Below these are two main regions separated by a central gap, each containing a substrate-like material 26 and a lower layer 27. These are further divided into sections 10 and 16. A thick bottom layer is labeled 30, with specific features 31 and 32 indicated. Various other components and interfaces are labeled with numbers 4, 5, 6, 7, and C3. Arrows point from labels A3 and C3 towards specific parts of the device.



FIG.6a

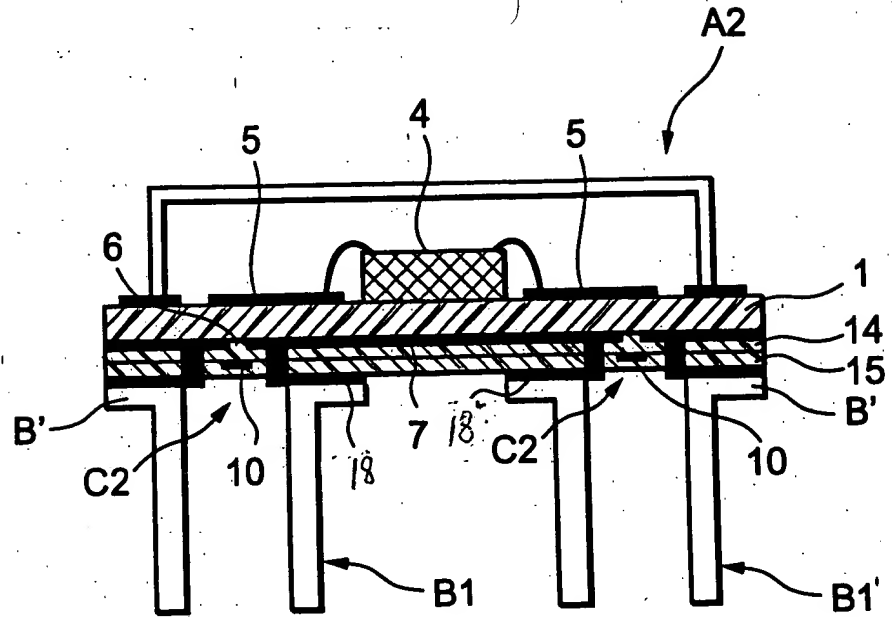


FIG.6b

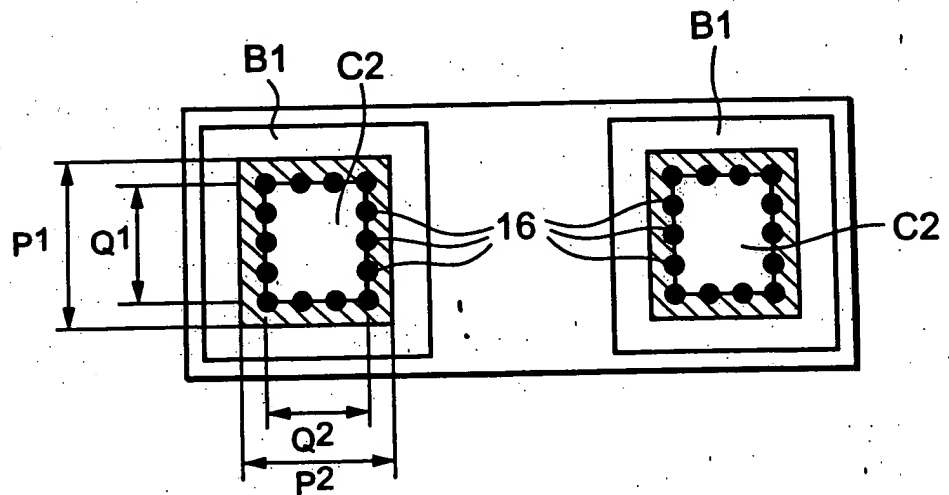


FIG.6c

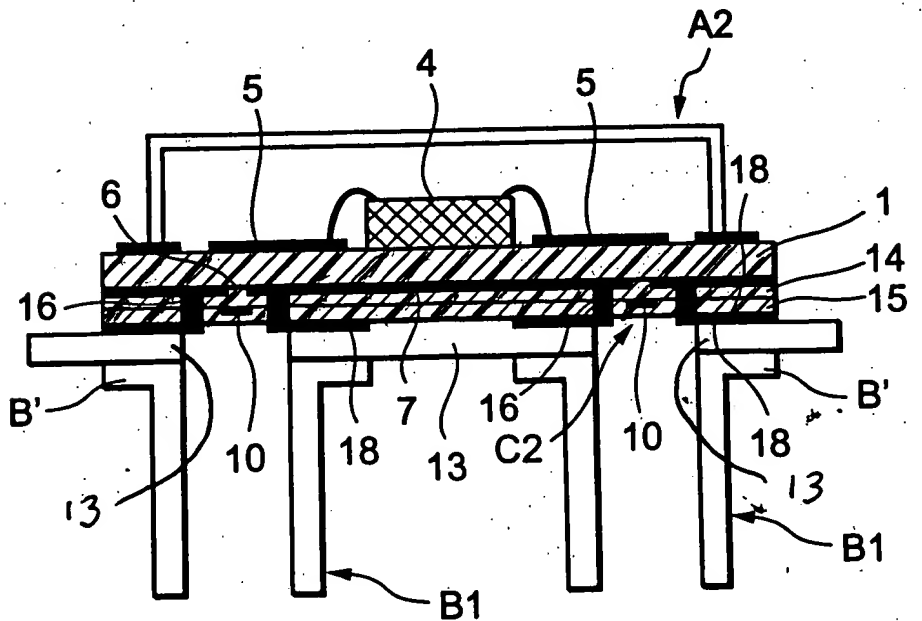


FIG.7

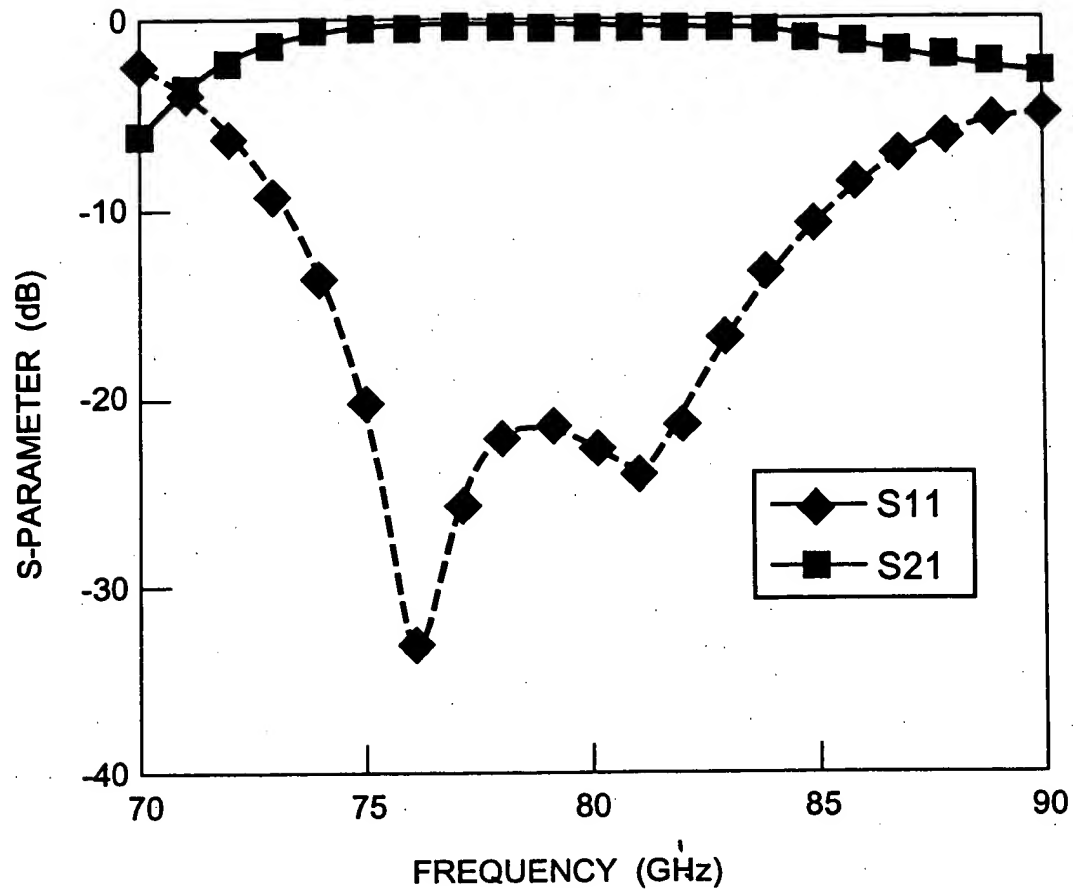


FIG.8

